

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Do-Hyung Kim	11/07/2008
Byoung-Ha Oh	12/26/2008
Young-Jun Park	12/26/2008
Yong-Ho Ko	11/07/2008
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd.
Street Address:	416, Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12221728
CORRESPONDENCE DATA	
Fax Number:	(617)742-7774
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	617-994-4900
Email:	mail@millsonello.com
Correspondent Name:	MILLS & ONELLO LLP
Address Line 1:	Eleven Beacon Street, Suite 605
Address Line 4:	Boston, MASSACHUSETTS 02108
ATTORNEY DOCKET NUMBER:	SAM-1271
NAME OF SUBMITTER:	David M. Mello
<p>Total Attachments: 4</p> <p>source=1271_Assignment#page1.tif</p> <p>source=1271_Assignment#page2.tif</p>	

OP \$40.00 12221728

500743684

PATENT
REEL: 022045 FRAME: 0480

ASSIGNMENT

We, Do-Hyung Kim, of 303-707, Dodam Maeul Umi Innosville, Jukjeon-dong, Suji-gu, Yongin-si, Gyeonggi-do, Republic of Korea; Byoung-Ha Oh, of 105-602, Chamsol Maeul World Meridian, Jung-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea; Young-Jun Park, of 105-1106, Indeokwon Samsung Apt., Gwanyang 2-dong, Dongan-gu, Anyang-si, Gyeonggi-do, Republic of Korea; and Yong-Ho Ko, 210-902, Byoksan 2-Danji Apt., Jukjeon 2-dong, Suji-gu, Yongin-si, Gyeonggi-do, Republic of Korea; having invented improvements in MEMORY MODULE HAVING STAR-TYPE TOPOLOGY AND METHOD OF FABRICATING THE SAME described in an application for Letters Patent of the United States, Serial No. 12/221,728, filed August 6, 2008 for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application; and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;


And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

First or Sole Inventor:

Signature:


Do-Hyung Kim

Date: 2008/11/07

Second Joint Inventor:

Signature:

Byoung-Ha Oh

Date: _____

Third Joint Inventor:

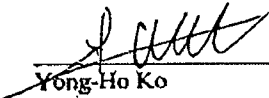
Signature:

Young-Jun Park

Date: _____

Fourth Joint Inventor:

Signature:


Yong-Ho Ko

Date: 2008/11/07

REFERENCE NO. : SAM-1271
J:\SAM\1271\update\data\signature-multi-inv.vpd

First or Sole Inventor:

Signature: _____
Do-Hyung Kim

Date: _____

Second Joint Inventor:

Signature:  _____
Byoung-Ha Oh

Date: 2008.12.26

Third Joint Inventor:

Signature: _____
Young-Jun Park

Date: _____

Fourth Joint Inventor:

Signature: _____
Yong-Ho Ko

Date: _____

REFERENCE NO. : SAM-1271
J:\SAM\1271\update\ass\invent-multi-inv.wpd

First or Sole Inventor:

Signature: Do-Hyung Kim

Date: _____

Second Joint Inventor:

Signature: Byoung-Ha Oh

Date: _____

Third Joint Inventor:

Signature: YOUNG-JUN PARK
Young-Jun Park

Date: 2008.12.26

Fourth Joint Inventor:

Signature: Yong-Ho Ko

Date: _____

REFERENCE NO. : SAM-1271
J:\SAM\1271\update\design\mult-lav.wpd